| ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Par | PC, Bannock | burn, Illinois. A | Il rights reserved nations. | under both | This docum level parts, t | ent is a declara he declaration | tion of the s encompasse | ubstances es all lowe | within the manuar r level materials | Cacturer liste for which th | d item. Note: e manufacture | if the item is an a r has engineering | ssembly with low responsibility. | |
|--|---|-------------------|-----------------------------|-------------------------|------------------------------|--|-----------------------------|--------------------------|--|---------------------------------------|---------------------------------|--|----------------------------------|--|
| | IPC Web Site for Information on IPC-1752 Standard Form 7 http://www.ipc.org/IPC-175x Distrib | | | | • * | * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi | | | | laterials and | als and Mfg Information | | | |
| Supplier Information | | | | | | | | | | | | | | |
| Company name* Co | | | Company unique ID | | | Unique ID Authority | | | | Resp | Response Date* | | | |
| semi | | | | | | | | | | | 2024-05-21 | | | |
| Contact Name | ct Name Title - Contact | | | Phone | | | none - Contact* | | | Emai | Email - Contact* | | | |
| Product-Env-Stewards | duct-Env-Stewards Product Enviro | | | ro Compliance | | | NA | | | | Product-Env-Stewards@onsemi.com | | | |
| thorized Representative* Title - Representati | | | entative ! | | Phone - Representative* | | | Emai | Email - Representative* | | | | | |
| Product-Env-Stewards Product | | | roduct Enviro Compliance | | | NA | | | | Prod | Product-Env-Stewards@onsemi.com | | | |
| Requester Item Number | Mfr Iten | n Number | Mfr Item Name | | | Effective Dat | e Version |] | Manufacturing Site | | Weight* | UOM | Unit Type | |
| | NVMFS T3G | | | ET SO8FL 60V 235A 1.5MO | | 2024-05-21 | |] | MY1 | | 107.2528 | mg | Each | |
| Aanufacturing Proccess Informat | tion | | | | | | | | | | | | | |
| Terminal Plating / Grid Array Ma | Grid Array Material Terminal Base | | Alloy | J-STD-020 MSL Rating | | Peak Process Body Temperature M | | re Max Time at | Peak Tempe | k Temperature Number of Reflow Cycles | | cles | | |
| Matte Tin (Sn) - annealed CU Alloy | | | 1 | | 260 | | С | 30 | sec | conds 3 | | | | |
| omments | | | | | | | | | | | | | | |
| vel 1 - maximum time at peak temperatu | re during so | Idering is 10-3 | 0 seconds | | | | | | | | | | | |
| or more information regarding material | composition | please refer to | page 3 | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | |
|--|---|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). | | | | | | | | | |
| cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the | henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg | nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co | e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica | ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | | |
| RoHS Declaration * 4 - Item(| s) does not contain RoHS restricted subst | ances per the definition above except for sele | ected exempt | ions Supplier Acceptance | * Accepted | | | | | |
| Exemption: 7a: Lead in high melting temp | erature type solders (i.e. lead based sol | der alloys containing 85% by weight or m | ore lead). | | | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | |
| Declaration Signature | | | | | | | | | | |
| Instructions: Complete all of the required Requester) and click on Submit Form to h | | | e drop-dowi | a. This will display the signature area. Digita | lly sign the declaration (if required by the | | | | | |
| Supplier Digital Signature | astislav Drska | Le | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|---------|-----------------|----------|-------------------------|------------------|--------|---------|-----------------|
| Clip | 13.512 | mg | Supplier | Zinc (Zn) | 7440-66-6 | | 0.0162 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.3175 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 13.1742 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.0041 | mg |
| Die | 0.727 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 0.727 | mg |
| Die Attach Solder | 1.4993 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.0375 | mg |
| | | | А | Lead (Pb) | 7439-92-1 | 7a | 1.3869 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.075 | mg |
| Lead Frame | 42.5398 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.0255 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.0425 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 42.459 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.0128 | mg |
| Mold Compound-Black | 48.7198 | mg | | Epoxy resin | proprietary data | | 3.654 | mg |
| | | | Supplier | Phenolic Resin | Proprietary Data | | 1.218 | mg |
| | | | Supplier | Silica Amorphous (SiO2) | 7631-86-9 | | 3.654 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 0.2436 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 39.9502 | mg |
| Plating | 0.2183 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 0.2183 | mg |
| Wire Bond - Cu | 0.0366 | mg | Supplier | Copper (Cu) | 7440-50-8 | | 0.0366 | mg |